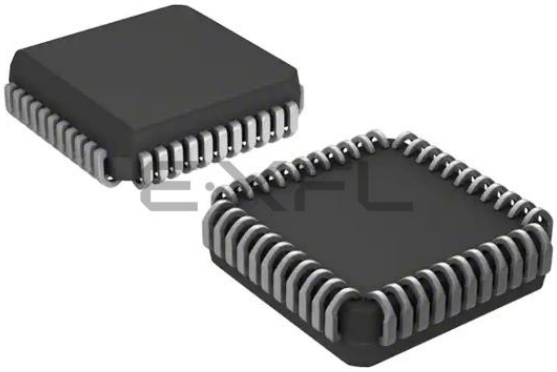

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	Z8
Core Size	8-Bit
Speed	12MHz
Connectivity	EBI/EMI
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	236 x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8674312vsg

Pin Description

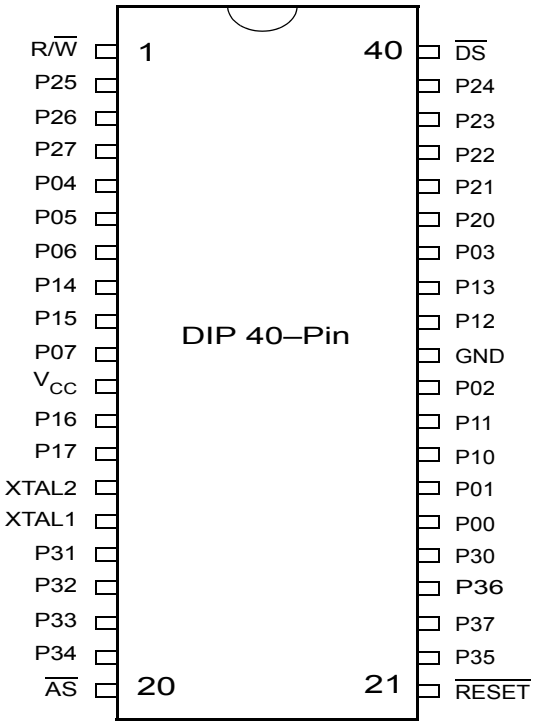

Figure 3. 40-Pin DIP Pin Configuration Standard Mode

Table 2. 40-Pin DIP Pin Identification Standard Mode

Pin No	Symbol	Function	Direction
1	R/$\overline{W}$	Read/Write	Output
2-4	P25-P27	Port 2, Pins 5,6,7	Input/Output
5-7	P04-P06	Port 0, Pins 4,5,6	Input/Output
8-9	P14-P15	Port 1, Pins 4,5	Input/Output
10	P07	Port 0, Pin 7	Input/Output
11	V_{CC}	Power Supply	
12-13	P16-P17	Port 1, Pins 6,7	Input/Output
14	XTAL2	Crystal Oscillator	Output

Table 2. 40-Pin DIP Pin Identification Standard Mode (Continued)

Pin No	Symbol	Function	Direction
15	XTAL1	Crystal Oscillator	Input
16-18	P31-P33	Port 3, Pins 1,2,3	Input
19	P34	Port 3, Pin 4	Output
20	AS	Address Strobe	Output
21	RESET	Reset	Input
22	P35	Port 3, Pin 5	Output
23	P37	Port 3, Pin 7	Output
24	P36	Port 3, Pin 6	Output
25	P30	Port 3, Pin 0	Input
26-27	P00-P01	Port 0, Pins 0,1	Input/Output
28-29	P10-P11	Port 1, Pins 0,1	Input/Output
30	P02	Port 0, Pin 2	Input/Output
31	GND	Ground	
32-33	P12-P13	Port 1, Pins 2,3	Input/Output
34	P03	Port 0, Pin 3	Input/Output
35-39	P20-P24	Port 2, Pins 0, 1,2,3,4	Input/Output
40	DS	Data Strobe	Output

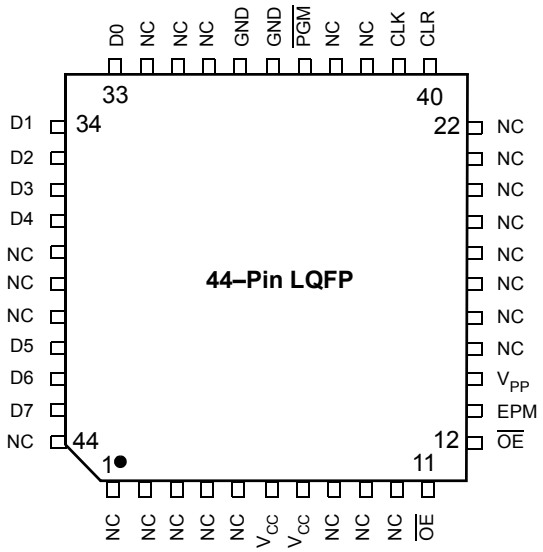

Figure 8. 44-Pin LQFP Pin Configuration EPROM Programming Mode

Table 7. 44-Pin LQFP Pin Identification EPROM Programming Mode

Pin No	Symbol	Function	Direction
1-5	NC	No Connection	
6-7	V_{CC}	Power Supply	
8-10	NC	No Connection	
11	CE	Chip Select	Input
12	OE	Output Enable	Input
13	EPM	EPROM Prog. Mode	Input
14	V_{PP}	Prog. Voltage	Input
15-22	NC	No Connection	
23	CLR	Clear	Input
24	CLK	Clock	Input
25-26	NC	No Connection	
27	/PGM	Prog. Mode	Input
28-29	GND	Ground	
30-32	NC	No Connection	

Electrical Characteristics

Absolute Maximum Ratings

Table 10. Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.6	+7	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on XTAL1, P32, P33 and $\overline{\text{RESET}}$ Pins with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		1.21	W	
Maximum Allowable Current out of V_{SS}		220	mA	
Maximum Allowable Current into V_{DD}		180	mA	
Maximum Allowable Current into an Input Pin	–600	+600	µA	3
Maximum Allowable Current into an Open-Drain Pin	–600	+600	µA	4
Maximum Allowable Output Current Sunk by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sunk by $\overline{\text{RESET}}$ Pin		3	mA	

Notes
1. This applies to all pins except XTAL pins and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. This excludes XTAL pins.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

Table 12. DC Electrical Characteristics T_A= -40 °C to +105 °C (Continued)

Symbol	Parameter	V_{CC} [1]	Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC2}	Standby Current STOP Mode	4.5V		10	2	µA	V_{IN} = 0V, V_{CC}	7,8,9
		5.5V		10	3	µA	V_{IN} = 0V, V_{CC}	7,8,9
		4.5V		40	10	µA	V_{IN} = 0V, V_{CC}	7,8
		5.5V		40	10	µA	V_{IN} = 0V, V_{CC}	7,8
I_{ALL}	Auto Latch Low Current	4.5V	1.4	20	4.7	µA	0V < V_{IN} < V_{CC}	10
		5.5V	1.4	20	4.7	µA	0V < V_{IN} < V_{CC}	10
I_{ALH}	Auto Latch High Current	4.5V	-1.0	-10	-3.8	µA	0V < V_{IN} < V_{CC}	10
		5.5V	-1.0	-10	-3.8	µA	0V < V_{IN} < V_{CC}	10
T_{POR}	Power-On Reset	4.5V	1.0	14	4	ms		
		5.5V	1.0	14	4	ms		
V_{LV}	Auto Reset Voltage		2.0	3.3	2.8	V		11

Notes

1. The V_{CC} voltage specification of 5.5 V guarantees 5.0 V ± 0.5 V and the V_{CC} voltage specification of 3.5 V guarantees only 3.5 V.
2. STD Mode (not Low EMI Mode).
3. Z86E43/743/E44 only.
4. For analog comparator inputs when analog comparators are enabled.
5. All outputs unloaded, I/O pins floating, inputs at rail.
6. CL1=CL2=22 pF.
7. Same as note 5 except inputs at V_{CC}.
8. Clock must be forced Low, when XTAL1 is clock driven and XTAL2.
9. WDT is not running.
10. Auto Latch (mask option) selected.
11. Device does function down to the Auto Reset voltage.

Table 14. DC Electrical Characteristics T_A = -40 °C to +105 °C, 12 MHz (Continued)

No.	Symbol	Parameter	V_{CC}[1]	Min	Max	Units	Notes
10	TdDS(A)	$\overline{DS}$ Rise to Address Active Delay	4.5V	45		ns	2
			5.5V	55		ns	2
11	TdDS(AS)	$\overline{DS}$ Rise to $\overline{AS}$ Fall Delay	4.5V	45		ns	2
			5.5V	45		ns	2
12	TdR/W(AS)	R/$\overline{W}$ Valid to $\overline{AS}$ Rise Delay	4.5V	45		ns	2
			5.5V	45		ns	2
13	TdDS(R/W)	$\overline{DS}$ Rise to R/$\overline{W}$ Not Valid	4.5V	45		ns	2
			5.5V	45		ns	2
14	TdDW(DSW)	Write Data Valid to $\overline{DS}$ Fall (Write) Delay	4.5V	55		ns	2
			5.5V	55		ns	2
15	TdDS(DW)	$\overline{DS}$ Rise to Write Data Not Valid Delay	4.5V	55		ns	2
			5.5V	55		ns	2
16	TdA(DR)	Address Valid to Read Data Req'd Valid	4.5V		310	ns	2,3
			5.5V		310	ns	2,3
17	TdAS(DS)	$\overline{AS}$ Rise to $\overline{DS}$ Fall Delay	4.5V	65		ns	2
			5.5V	65		ns	2
18	TdDM(AS)	$\overline{DM}$ Valid to $\overline{AS}$ Rise Delay	4.5V	35		ns	2
			5.5V	35		ns	2
19	ThDS(AS)	$\overline{DS}$ Valid to Address Valid Hold Time	4.5V	35		ns	2
			5.5V	35		ns	2

Notes

1. The V_{CC} voltage specification of 5.5 V guarantees 5.0 V ± 0.5 V and the V_{CC} voltage specification of 3.5 V guarantees only 3.5 V.
2. Timing numbers given are for minimum TpC.
3. When using extended memory timing, add 2 TpC.

Standard Test Load

All timing references use 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.

For Standard Mode (not Low-EMI Mode for outputs) with SMR, D1 = 0, D0 = 0.

CLR Clear (active High). This pin resets the internal address counter at the High Level.

CLK Address Clock. This pin is a clock input. The internal address counter increases by one for each clock cycle.

Application Precaution

The production test-mode environment may be enabled accidentally during normal operation if excessive noise surges above V_{CC} occur on pins P31 and $\overline{\text{RESET}}$.

In addition, processor operation of Z8 OTP devices may be affected by excessive noise surges on the V_{PP}, EPM, $\overline{\text{OE}}$ pins while the microcontroller is in Standard Mode.

Recommendations for dampening voltage surges in both test and OTP mode include the following:

- Using a clamping diode to V_{CC}
- Adding a capacitor to the affected pin
- Enable EPROM/Test Mode Disable OTP option bit.

Standard Mode

XTAL Crystal 1 (time-based input). This pin connects a parallel-resonant crystal, ceramic resonator, LC, RC network, or external single-phase clock to the on-chip oscillator input.

XTAL2 Crystal 2 (time-based output). This pin connects a parallel-resonant crystal, ceramic resonator, LC, or RC network to the on-chip oscillator output.

R/$\overline{\text{W}}$ Read/Write (output, write Low). The R/$\overline{\text{W}}$ signal is Low when the CCP is writing to the external program or data memory (Z86E43/743/E44 only).

$\overline{\text{RESET}}$ Reset (input, active Low). Reset will initialize the MCU. Reset is accomplished either through Power-On, Watchdog Timer reset, Stop Mode Recovery, or external reset. During Power-On Reset and Watchdog Timer Reset, the internally generated reset drives the reset pin low for the POR time. Any devices driving the reset line must be open-drain in order to avoid damage from a possible conflict during reset conditions. Pull-up is provided internally. After the POR time, $\overline{\text{RESET}}$ is a Schmitt-triggered input. ($\overline{\text{RESET}}$ is available on Z86E43/743/E44 only.)

To avoid asynchronous and noisy reset problems, the Z86E43/743/E44 is equipped with a reset filter of four external clocks (4TpC). If the external reset signal is less than 4TpC in duration, no reset occurs. On the fifth clock after the reset is detected, an internal RST signal is latched and held for an internal register count of 18 external clocks, or for the duration of the external reset, whichever is longer. During the reset cycle, $\overline{\text{DS}}$ is held active Low while $\overline{\text{AS}}$ cycles at a rate of TpC/2. Program execution begins at location 000CH, 5-10 TpC cycles after $\overline{\text{RESET}}$ is released. For Power-On Reset, the reset output time is 5 ms.

The Z86E43/743/E44 does not reset WDTMR, SMR, P2M, and P3M registers on a Stop-Mode Recovery operation.

$\overline{\text{ROMless}}$ (input, active Low). This pin, when connected to GND, disables the internal ROM and forces the device to function as a Z86C90/C89 ROMless Z8. (Note that, when left unconnected or pulled High to V_{CC}, the device functions nor

Note: *When using in ROM Mode in High EMI (noisy) environment, the ROMless pins should be connected directly to V_{CC}.*

$\overline{\text{DS}}$ (output, active Low). Data Strobe is activated once for each external memory transfer. For a READ operation, data must be available prior to the trailing edge of $\overline{\text{DS}}$. For WRITE operations, the falling edge of $\overline{\text{DS}}$ indicates that output data is valid.

$\overline{\text{AS}}$ (output, active Low). Address Strobe is pulsed once at the beginning of each machine cycle for external memory transfer. Address output is from Port 0/Port 1 for all external programs. Memory address transfers are valid at the trailing edge of $\overline{\text{AS}}$. Under program control, $\overline{\text{AS}}$ is placed in the high-impedance state along with Ports 0 and 1, Data Strobe, and Read/Write.

Port 0 (P07-P00). Port 0 is an 8-bit, bidirectional, CMOS-compatible I/0 port. These eight I/O lines can be configured under software control as a nibble I/0 port, or as an address port for interfacing external memory. The input buffers are Schmitt-triggered and nibble programmed. Either nibble output that can be globally programmed as push-pull or open-drain. Low EMI output buffers can be globally programmed by the software. Port 0 can be placed under handshake control. In Handshake Mode, Port 3 lines P32 and P35 are used as handshake control lines. The handshake direction is determined by the configuration (input or output) assigned to Port 0's upper nibble. The lower nibble must have the same direction as the upper nibble.

For external memory references, Port 0 provides address bits A11-A8 (lower nibble) or Al 5-A8 (lower and upper nibble) depending on the required address space. If the address range requires 12 bits or less, the upper nibble of Port 0 can be programmed independently as I/O while the lower nibble is used for addressing. If one or both nibbles are needed for I/O operation, they must be configured by writing to the Port 0 mode register. In ROMless mode, after a hardware reset, Port 0 is configured as address lines Al 5-A8, and extended timing is set to accommodate slow memory access. The initialization routine can include re-configuration to eliminate this extended timing mode. In ROM mode, Port 0 is defined as input after reset.

Port 0 can be set in the High-Impedance Mode if selected as an address output state, along with Port 1 and the control signals $\overline{\text{AS}}$, $\overline{\text{DS}}$, and R/$\overline{\text{W}}$ (Figure 18).

and P32 with reference to the voltage on P33. The analog function is enabled by setting the D1 of Port 3 Mode Register (P3M). The comparator output can be outputted from P34 and P37, respectively, by setting PCON register Bit D0 to 1 state. For the interrupt function, P30 and P33 are falling edge triggered interrupt inputs. P31 and P32 can be programmed as falling, rising or both edges triggered interrupt inputs (see Figure 21). Access to Counter/Timer 1 is made through P31 (T_{IN}) and P36 (T_{OUT}). Handshake tines for Port 0, Port 1, and Port 2 are also available on Port 3 (see Table 19).

Note: *When enabling or disabling analog mode, the following is recommended:*

1. Allow two NOP decays before reading this comparator output.
2. Disable global interrupts, switch to analog mode, clear interrupts, and then re-enable interrupts.
3. IRQ register bits 3 to 0 must be cleared after enabling analog mode.

Note: *P33-P30 differs from the Z86C33/C43/233/243 in that there is no clamping diode to V_{CC} due to the EPROM high-voltage circuits. Exceeding the V_{IH} maximum specification during standard operating mode may cause the device to enter EPROM mode.*

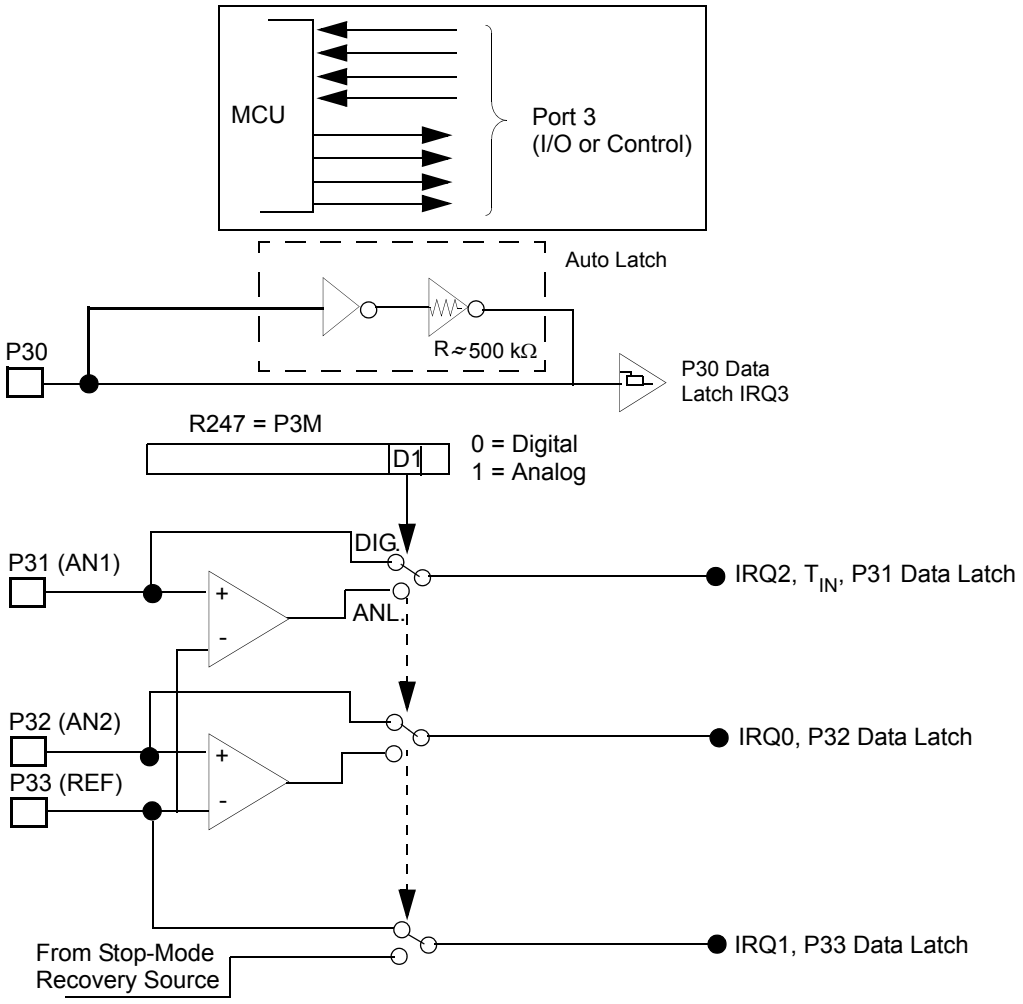

Figure 21. Port 3 Configuration

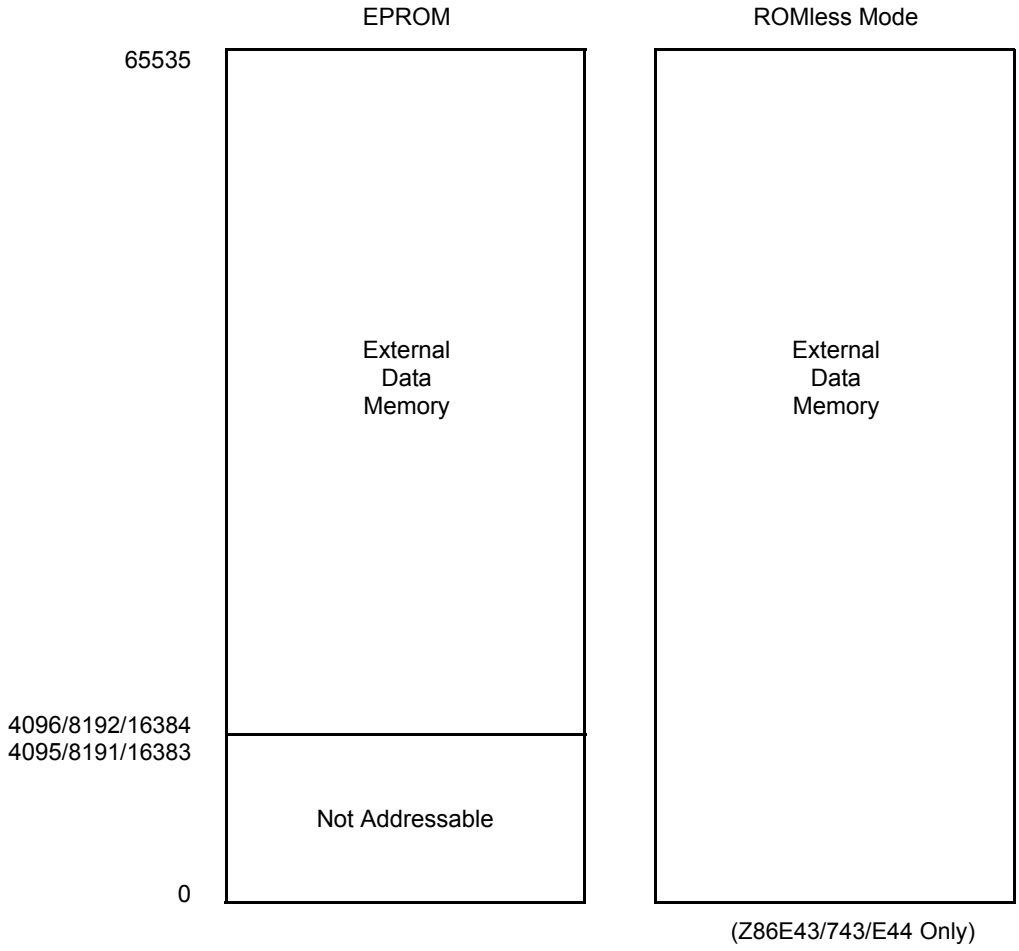

Figure 23. Data Memory Map

Register File. The register file consists of three I/O port registers, 236/125 general-purpose registers, 15 control and status registers, and three system configuration registers in the expanded register group. The instructions can access registers directly or indirectly through an 8-bit address field. This allows a short 4-bit register address using the Register Pointer (see Figure 24). In the 4-bit mode, the register file is divided into 16 working register groups, each occupying 16 continuous locations. The Register Pointer addresses the starting location of the active working-register group.

Note: *Register Group E0-EF can only be accessed through working register and indirect addressing modes.*

When more than one interrupt is pending, priorities are resolved by a programmable priority encoder that is controlled by the Interrupt Priority Register (IPR). An interrupt machine cycle is activated when an interrupt request is granted. Thus, disabling all subsequent interrupts, saves the Program Counter and Status Flags, and then branches to the program memory vector location reserved for that interrupt. All interrupts are vectored through locations in the program memory. This memory location and the next byte contain the 16-bit starting address of the interrupt service routine for that particular interrupt request.

To accommodate polled interrupt systems, interrupt inputs are masked and the interrupt request register is polled to determine which of the interrupt requests need service.

An interrupt resulting from AN1 is mapped into IRQ2, and an interrupt from AN2 is mapped into IRQ0. Interrupts IRQ2 and IRQ0 may be rising, falling or both edge triggered, and are programmable by the user. The software may poll to identify the state of the pin.

Programming bits for the Interrupt Edge Select are located in bits D7 and D6 of the IRQ Register (R250). The configuration is shown in Table 21.

Table 21. IRQ Register Configuration

IRO		Interrupt Edge	
D7	**D6**	**P31**	**P32**
0	0	F	F
0	1	F	R
1	0	R	F
1	1	R/F	R/F

Notes
1. F = Falling Edge
2. R = Rising Edge

Clock. The on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a crystal, RC, ceramic resonator, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal should be AT cut, 10 kHz to 16 MHz max, with a series resistance (RS) less than or equal to 100 Ω.

The crystal should be connected across XTAL1 and XTAL2 using the vendor's recommended capacitor values from each pin directly to device pin Ground. The RC oscillator option can be selected in the programming mode. The RC oscillator configuration must be an external resistor connected from XTAL1 to XTAL2, with a frequency-setting capacitor from XTAL1 to Ground (Table 29).

```
FF    NOP    ; clear the pipeline
6F    STOP   ; enter STOP mode
```

or

```
FF    NOP    ; clear the pipeline
7F    HALT   ; enter HALT mode
```

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 microamperes or less. STOP Mode is terminated by one of the following resets: either by WDT time-out, POR, a Stop Mode Recovery Source, which is defined by the SMR register or external reset. This causes the processor to restart the application program at address 000Ch.

Port Configuration Register (PCON). The PCON register configures the ports individually; comparator output on Port 3, open-drain on Port 0 and Port 1, low EMI on Ports 0, 1, 2 and 3, and low EMI oscillator. The PCON register is located in the expanded register file at Bank F, location 00 (Figure 30).

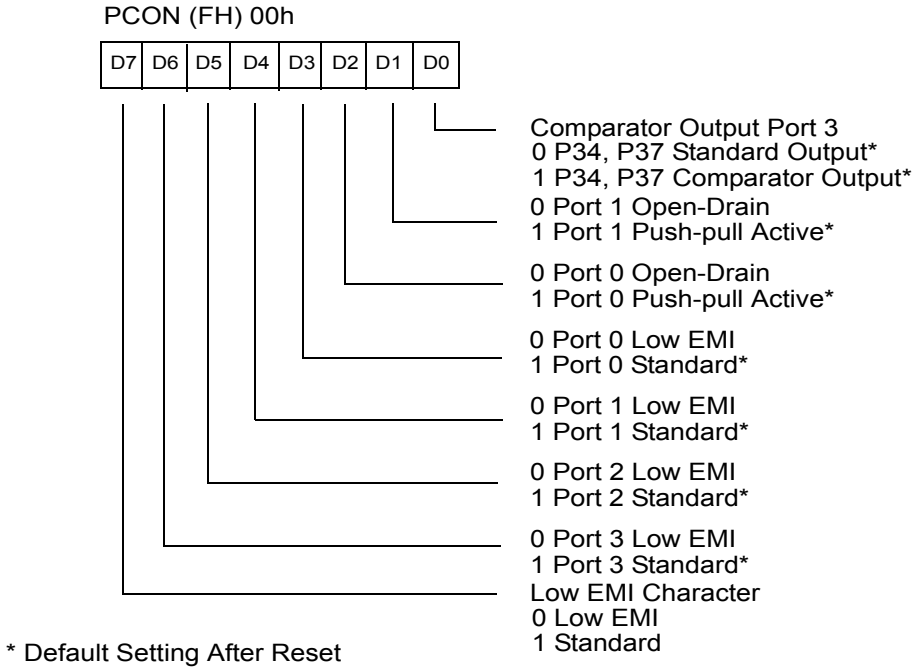

Figure 30. Port Configuration Register (PCON) (Write Only)

Comparator Output Port 3 (D0). Bit 0 controls the comparator output in Port 3. A "1" in this location brings the comparator outputs to P34 and P37, and a "0" releases the Port to its standard I/O configuration. The default value is 0.

Port 1 Open-Drain (D1). Port 1 can be configured as an open-drain by resetting this bit (D1=0) or configured as push-pull active by setting this bit (D1=1). The default value is 1.

Port 0 Open-Drain (D2). Port 0 can be configured as an open-drain by resetting this bit (D2=0) or configured as push-pull active by setting this bit (D2=1). The default value is 1.

Low EMI Port 0 (D3). Port 0 can be configured as a Low EMI Port by resetting this bit (D3=0) or configured as a Standard Port by setting this bit (D3=1). The default value is 1.

Low EMI Port 1 (D4). Port 1 can be configured as a Low EMI Port by resetting this bit (D4=0) or configured as a Standard Port by setting this bit (D4=1). The default value is 1.

Note: *The emulator does not support Port 1 low EMI mode and must be set D4 = 1.*

Low EMI Port 2 (D5). Port 2 can be configured as a Low EMI Port by resetting this bit (D5=0) or configured as a Standard Port by setting this bit (D5=1). The default value is 1.

Low EMI Port 3 (D6). Port 3 can be configured as a Low EMI Port by resetting this bit (D6=0) or configured as a Standard Port by setting this bit (D6=1). The default value is 1.

Low EMI OSC (D7). This bit of the PCON Register controls the low EMI noise oscillator. A "1" in this location configures the oscillator with standard drive. While a "0" configures the oscillator with low noise drive, however, it does not affect the relationship of SCLK and XTAL. The low EMI mode will reduce the drive of the oscillator (OSC). The default value is 1.

Note: *4 MHz is the maximum external clock frequency when running in the low EMI oscillator mode.*

Stop-Mode Recovery Register (SMR). This register selects the clock divide value and determines the mode of Stop Mode Recovery (Figure 31). All bits are Write Only except bit 7 which is a Read Only. Bit 7 is a flag bit that is hardware set on the condition of STOP Recovery and reset by a power-on cycle. Bit 6 controls whether a low or high level is required from the recovery source. Bit 5 controls the reset delay after recovery. Bits 2, 3, and 4 of the SMR register specify the Stop Mode Recovery Source. The SMR is located in Bank F of the Expanded Register File at address 0BH.

from STOP mode when programmed as analog inputs. When the Stop Mode Recovery sources are selected in this register then SMR2 register bits D0, D1 must be set to zero.

Note: *If the Port 2 pin is configured as an output, this output level will be read by the SMR circuitry.*

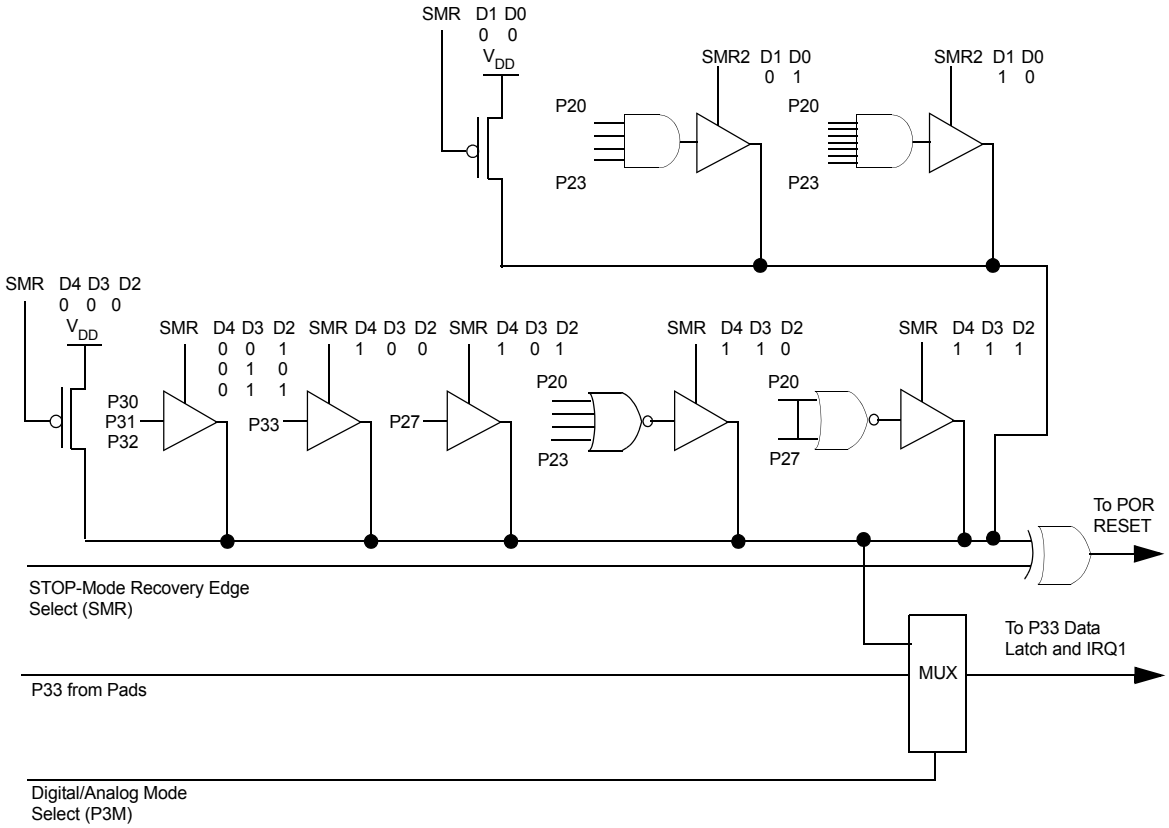

Figure 32. Stop Mode Recovery Source

Reset and initially enabled by executing the WDT instruction and refreshed on subsequent executions of the WDT instruction. The WDT is driven either by an on-board RC oscillator or an external oscillator from XTAL1 pin. The POR clock source is selected with bit 4 of the WDT register.

Note: *Execution of the WDT instruction affects the Z (Zero), S (Sign), and V (Overflow) flags.*

WDT Time-Out Period (D0 and D1). Bits 0 and 1 control a tap circuit that determines the time-out periods that can be obtained (Table 23). The default value of DO and Dl are 1 and 0, respectively.

Table 23. Time-out Period of WDT

D1	DO	Time-out of the Internal RC OSC	Time-out of the System Clock
0	0	5 ms	128 SCLK
0	1	10 ms[1]	256 SCLK[1]
1	0	20 ms	512 SCLK
1	1	80 ms	2048 SCLK

Note: The default setting is 10 ms.

WDT During HALT Mode (D2). This bit determines whether or not the WDT is active during HALT Mode. A “1” indicates that the WDT is active during HALT. A “0” disables the WDT in HALT Mode. The default value is “1 “. WDT During STOP Mode (D3). This bit determines whether or not the WDT is active during STOP mode. A “1” indicates active during STOP. A “0” disables the WDT during STOP Mode. This is applicable only when the WDT clock source is the internal RC oscillator.

Clock Source For WDT (D4). This bit determines which oscillator source is used to clock the internal POR and WDT counter chain. If the bit is a 1, the internal RC oscillator is bypassed and the POR and WDT clock source is driven from the external pin, XTAL1, and the WDT is stopped in STOP Mode. The default configuration of this bit is 0, which selects the RC oscillator.

Permanent WDT. When this feature is enabled, the WDT is enabled after reset and will operate in Run and HALT Mode. The control bits in the WDTMR do not affect the WDT operation. If the clock source of the WDT is the internal RC oscillator, then the WDT will run in STOP mode. If the clock source of the WDT is the XTAL1 pin, then the WDT will not run in STOP mode.

Note: *WDT time-out in STOP Mode will not reset SMR,SMR2,PCON, WDTMR, P2M, P3M, Ports 2 & 3 Data Registers, but will activate the T_{POR} delay.*

WDTMR Register Accessibility. The WDTMR register is accessible only during the first 60 internal system clock cycles from the execution of the first instruction after Power-On Reset, Watchdog reset or a Stop Mode Recovery (Figure 33 and Figure 34). After this point, the register cannot be modified by any means, intentional or otherwise. The WDTMR cannot be read and is located in Bank F of the Expanded Register File at address location 0Fh.

Clock Free WDT Reset. The WDT will enable the Z8 to reset the I/0 pins whenever the WDT times out, even without a clock source running on the XTAL1 and XTAL2 pins. WDTMR Bit D4 must be 0 for the clock Free WDT to work. The I/O pins will default to their default settings.

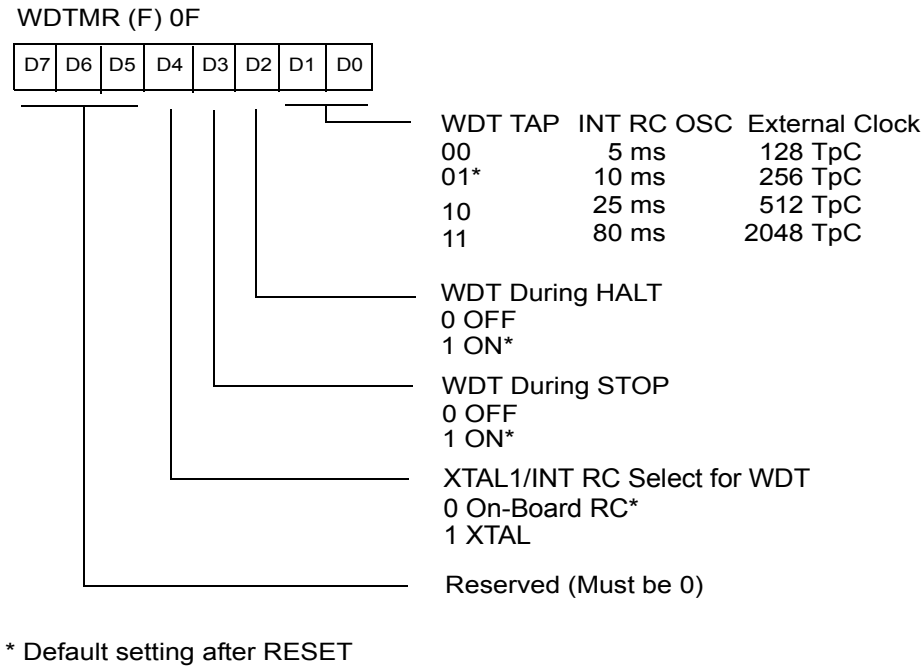

Figure 33. Watchdog Timer Mode Register Write Only

Z8 Control Register Diagrams

Ordering Information

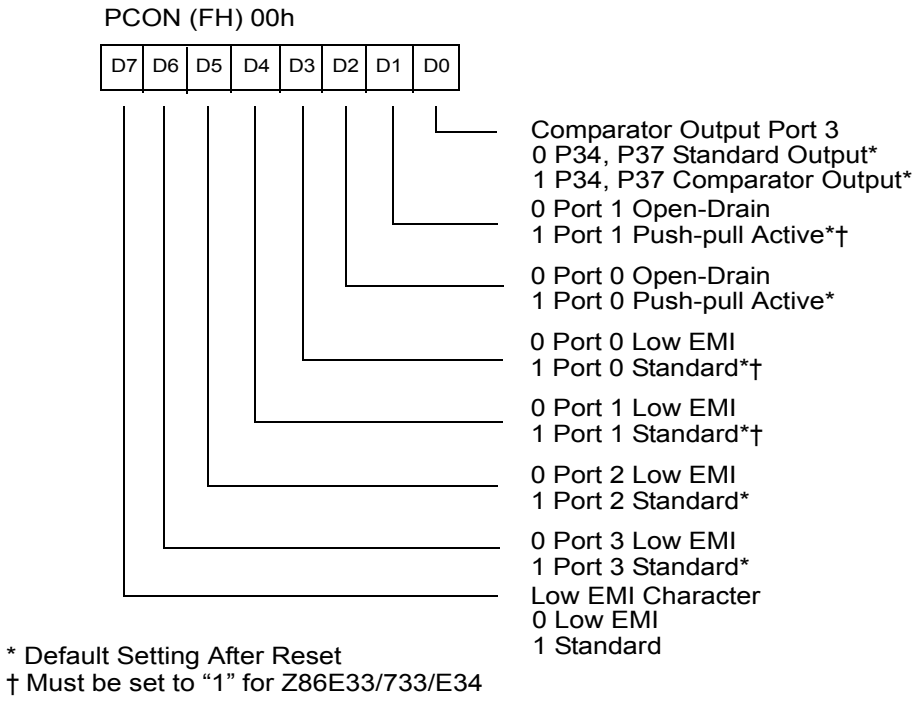

Figure 36. Port Configuration Register (PCON) (Write Only)

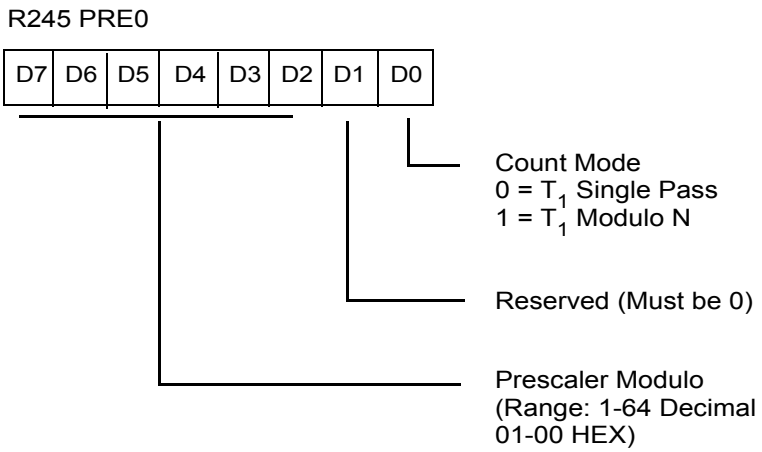

Figure 45. Prescaler 0 Register ($F5_h$: Write Only)

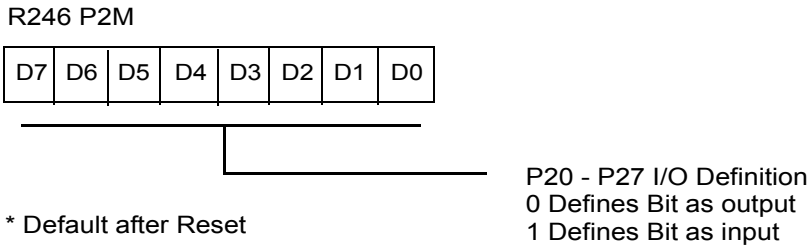

Figure 46. Port 2 Mode Register ($F6_h$: Write Only)

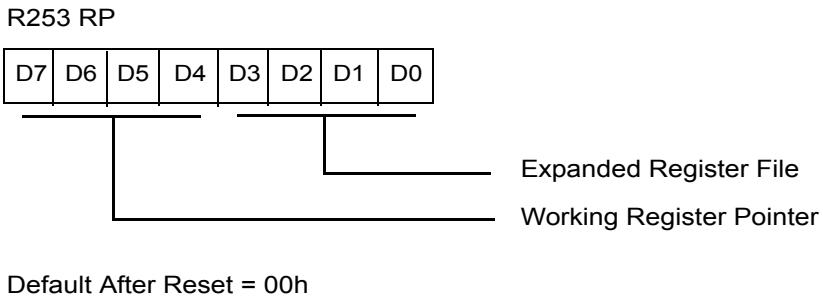

Figure 53. Register Pointer (FD_h: Read/Write)

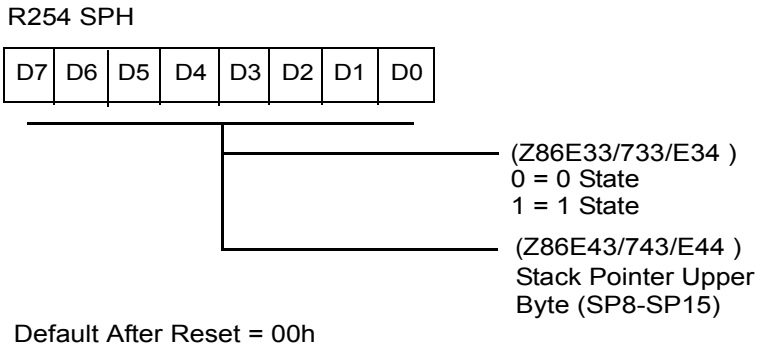

Figure 54. Stack Pointer High (FE_h: Read/Write)

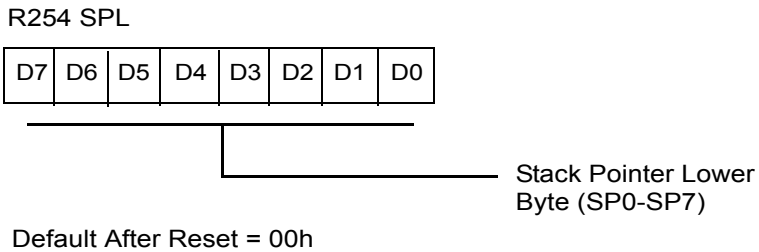

Figure 55. Stack Pointer Low (FF_h: Read/Write)